

ESL ELECTROSCIENCE

416 EAST CHURCH ROAD KING OF PRUSSIA, PA 19406-2625, U.S.A

T: 610-272-8000 F: 610-272-6759

www.electroscience.com

CERMET SILVER CONDUCTOR

Lead, Cadmium and Nickel-Free* **Excellent Fine-Line Capability**

ESL 9912-K FL is a fine-line printing silver conductor having a wide range of applications, for example chip resistors, consumer hybrids, potentiometers and heaters. It exhibits excellent line resolution printing 75 micrometer wide lines. Due to the wide firing temperature range, this conductor may be processed onto a variety of substrates including glass, Porcelain Enamelled Steel (PES), alumina and special ceramics.

PASTE DATA

Rheology:	Thixotropic, screen-printable paste
Viscosity : (Brookfield RVT, 10rpm, ABZ Spindle, 25.5 ± 0.5 °C)	310 ± 20 Pa.s
Bonding Mechanism:	Mixed-bonded
Shelf Life (20 - 25 °C):	6 months
PROCESSING	
Screen Mesh, Emulsion:	325 S/S, 25 μm
Levelling Time (at 20°C): Drying Time (at 125°C):	5 - 10 min 10 - 15 min
Firing Temperature Range:	On alumina/beryllia/ceramics:850 - 930°C in airOn Porcelain Enamelled Steel (PES):625°C in airOptimum (alumina):850°C in airOptimum (beryllia):930°C in airTime at peak:10 min
Total Firing Cycle:	1 hour
Substrate for Calibration:	96% alumina
Thinner:	ESL 401

(Note: furnace air must be clean, dry and oil-free)

ESL Europe 9912-K FL 0506-A

ESL Affiliates

ESL Europe (Agmet Ltd) • 8 Commercial Road • Reading • Berkshire • England • RG2 0QZ • Tel: +44 (0) 118 918 2400 • Fax: +44 (0) 118 986 7331 • Sales@ESLEurope.co.uk

ESL Nippon • Sukegawa Bldg. • 6th floor • 3-4 Yanagibashi 1-chome • Taito-ku • Tokyo 111, Japan • Tel: +81-3-3864-8521 • Fax: +81-3-3864-9270 • Sales@ESL-Nippon.co.jp ESL China • Room #1707, Tower A, City Center of Shanghai • 100 Zunyi Road • Shanghai, China 200051 • Tel: +86-21-6237-0336 and 0337 • Fax: +86-21-6237-0338

TYPICAL PROPERTIES (measurement on alumina after firing at 850°C)		
Fired Thickness: (measured on a 2 mm x 2 mm pad on 96% alumina)		2.5 ± 2.5 µm
Approximate Coverage:	100	- 125 cm²/g
Resistivity: (measured on a 100 mm x 0.25 mm conductor trac at 12.5 µm fired thickness)	k	< 2.5 mΩ/
Printing Resolution: (line/space)	0.075 mm	/ 0.075 mm
Solder Wettability: (RMA flux, 5 sec. dip, (62Sn/36Pb/2Ag, 220 °C)		100 %
Solder Leach: (No. of 10 sec. dips to double lowest resistance of 100 mm x 0.25 mm conductor, 62Sn/36Pb/2Ag, 22	0 °C)	> 5 dips
Adhesion: (90° pull, 2 mm x 2 mm pads, 62Sn/36Pb/2Ag)		
	Initial pull strength: (on most ceramic substrates)	> 7.0 kg
	Aged 48 hours at 150°C:	> 6.0 kg

*Complies with RoHS, ELV, WEEE and CHIP 3 EC directives.

CAUTION: Proper industrial safety precautions should be exercised in using these products. Use with adequate ventilation. Avoid prolonged contact with skin or inhalation of any vapours emitted during use or heating of these compositions. The use of safety eye goggles, gloves or hand protection creams is recommended. Wash hands or skin thoroughly with soap and water after using these products. Do not eat or smoke in areas where these materials are used. Refer to appropriate MSDS sheet.

DISCLAIMER: The product information and recommendations contained herein are based on data obtained by tests we believe to be accurate, but the accuracy and completeness thereof is not guaranteed. No warranty is expressed or implied regarding the accuracy of these data, the results obtained from the use hereof, or that any such use will not infringe any patent. ElectroScience assumes no liability for any injury, loss, or damage, direct or consequential, arising out of its use by others. This information is furnished upon the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular use, before using it. User assumes all risk and liability whatsoever in connection with his intended use. ElectroScience's only obligation shall be to replace such quantity of the product proved defective.